

Abstract

The invention discloses a method of electroplating a material onto a semiconductor substrate. A substrate is placed in a cylindrical processing chamber enclosure. A nozzle for spraying a liquid electroplating

5 solution opposes the top surface of the substrate. The electroplating solution flows through the nozzle and outward angularly from the tip of the nozzle, so that the solution flows rotationally on the surface of the substrate.

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